



Final Product/Process Change Notification

Document #:FPCN23597XH

Issue Date:04 May 2022

Title of Change:	Conversion of select onsemi, Czech Republic (Roznov) wafer fab technologies from 150mm to 200mm wafer diameter - LM158A family.	
Proposed First Ship date:	11 Aug 2022 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office or Jan.Gryzbon@onsemi.com	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local onsemi Sales Office or Tomas.Vajter@onsemi.com	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com	
Marking of Parts/ Traceability of Change:	The affected products will be identified with date code	
Change Category:	Wafer Fab Change	
Change Sub-Category(s):	Manufacturing Process Change	
Sites Affected:		
onsemi Sites		External Foundry/Subcon Sites
onsemi Roznov, Czech Republic		None

Description and Purpose:

Conversion of select onsemi, Czech Republic (Roznov) wafer fab technologies from 150mm to 200mm wafer diameter. The purpose is to increase the wafer fab productivity.

The 200mm wafer process has been created at Roznov in order to get the same electrical and reliability performances as the 150mm process. This is a change in wafer diameter only; there will be no changes to assembly or test locations as a result of this change.

A full electrical characterization over the temperature range has been performed for each product to check the device functionality and electrical specifications.

onsemi recommends that customers evaluate sample units in each associated application circuit to ensure there are no unexpected electrical incompatibilities.



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Reliability Data Summary:

QV DEVICE NAME : LM2904ADMR2G

RMS# : S78980

PACKAGE : Micro-8

Test	Specification	Condition	Interval	Results
HTOL	JA108	Ta= 125°C, Test @ R & H	1008 hrs	0/240
PC	JA112 JA113	SMD only, Test @ 0 & EP		0/351
SAT		Test pre- and post- PC		pass
ELFR	JA018	TA = 125°C for 48 hrs, Test @ R & H	48hrs	0/2400
TC	JA104	Test @ R & H	1000cyc	0/252
BS	AEC-Q100-001	Cpk 1.67, 30 bonds from 5units		pass
BPS	M883 Method 2011	3gm Pull Force Min After TC		pass
ESD HBM	AEC-Q100-002	c = 0, Test @ R & H	2kV	0/3
ESD CDM	AEC-Q100-011	c = 0, Test @ R	1kV	0/3
ED	ON Data Sheet	Cpk > 1.67 Test @ R, H, C	Cpk>1.67	pass
LU	AEC-Q100-004	Test @ EP; Test & Stress @ R & H	LU+>100mA LU->100mA	0/6

Electrical Characteristics Summary:

Electrical characteristics are not impacted. All Data Sheet specifications remain the same.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [**PCN Customized Portal**](#).

Part Number	Qualification Vehicle
LM358ADR2G	LM2904ADMR2G
LM358DMR2G	LM2904ADMR2G
LM2904VDMR2G	LM2904ADMR2G
LM2904DMR2G	LM2904ADMR2G
LM2904ADMR2G	LM2904ADMR2G
LM258DMR2G	LM2904ADMR2G